

✓ ~~sub 1~~  
electromagnetic interference suppressing body during use thereof in association with said electronic device.

- sub 2  
11. (Amended) The electronic device of claim 10, wherein said heat conductive powder is at least one selected from the group consisting of alumina ( $\text{Al}_2\text{O}_3$ ), aluminum nitride (AlN), cubic boron nitride (BN) and silicon carbide (SiC).

12. (Amendment) The electronic device of claim 11, wherein said organic binding agent is a thermoplastic resin having a glass transition temperature of not less than about  $120^\circ\text{C}$ .

- sub 3  
13. (Amended) The electronic device of claim 12, wherein said organic binding agent is at least one of thermoplastic polyamide and a liquid crystal polymer.

- sub 4  
14. (Amended) The electronic device of claim 13, wherein said electromagnetic interference suppressing article is in the form of a sheet, for use in contact with components to control the temperature thereof during use of said electronic device.


sub 5  
Please add the following claims. (NE)

- sub 6  
15. A combination of an electronic device, susceptible to and/or generating magnetic waves, and having adjacent thereto an electromagnetic interference suppressing

article, said article comprising:

13  
a first composite magnetic body, comprising a first soft magnetic powder and a first heat conductive powder dispersed through a first organic binding agent; and  
an electrically conductive support, mounted on said first composite magnetic body.--

-- 16. The electronic device of claim 15, further comprising a second composite magnetic body, mounted on said electrically conductive support, comprising a second soft magnetic powder and second heat conductive powder dispersed through a second organic binding agent.--

 -- 17. The electronic device of claim 15 or 16, wherein said electrically conductive support is at least one selected from the group consisting of a textile of electrically conductive fiber, an electric conductor plate, an electric conductor mesh plate, a textile of soft magnetic metal fiber, a soft magnetic metal plate, and a soft magnetic metal mesh plate.--

-- 18. The electronic device of claim 15 or 16, further comprising a heat sink mounted on the electromagnetic interference suppressing article.--

-- 19. The electronic device of claim 15, further comprising electrical components,

wherein said first composite magnetic body is mounted on said electrical components.--

Sub 7  
2a -- 20. The electronic device of claim 16, wherein said electrical components are in the form of an integrated circuit.--

-- 21. The electronic device of claim 20, wherein said integrated circuit is mounted on a circuit board.--

22  
containing  
-- 22. A method for suppressing magnetic waves comprising the steps of:  
providing a first composite magnetic body, comprising a soft magnetic powder and a heat conductive powder dispersed in an organic binding agent;  
attaching an electrically conductive support on said first composite magnetic body;  
providing an electronic device, susceptible to and/or generating magnetic waves; and  
positioning said first composite magnetic body adjacent to said electronic device.--

-- 23. The method of claim 21, further comprising the step of mounting a second composite magnetic body on said electrically conductive support.--

-- 24. The method of claim 21, wherein said electrically conductive support is at least one selected from the group consisting of a textile of electrically conductive fiber, an electric conductor plate, an electric conductor mesh plate, a textile of soft magnetic metal fiber, a soft magnetic metal plate, and a soft magnetic metal mesh plate.--

-- 25. The method of claim 22, further comprising a heat sink mounted on said electrically conductive support or said second composite magnetic body.--

*copy*  
-- 26. The method of claim 21, wherein said first composite magnetic body is mounted on an electronic device, susceptible to and/or generating magnetic waves.--

-- 27. The method of claim 21, wherein said first composite magnetic body is mounted on an integrated circuit.--